

422 Series

Thin Film Fuse, 2410 Fast Acting



Description

422 Series fuse is a 250 V rated Wire-in-Air Surface Mount Fuse, designed specifically to provide circuit protection to space constrained application. The wire-in-air design of the 422 Series results in a relatively high I^2t in a 2410 size.

Features & Benefits

- Operating Temperature from -55 °C to 125 °C
- 100% Lead-free, Halogen-Free and RoHS compliant
- Fast Acting
- Recognized to UL/CSA/NMX 248-1 and UL/CSA/NMX 248-14
- Conforms to EN/IEC 60127-1 and EN/IEC 60127-7
- Conforms to J60127-1 and J60127-7
- Avoids nuisance opening due to high inrush and surge current inherent in the system
- Suitable for harsh environments

Additional Information



Resources



Accessories



Samples

Applications

- Industrial equipment
- Backlight inverter
- Power supply
- Telecom
- Server
- Networking
- Gaming system
- White goods

Agency Approvals

Agency	Agency File/Certificate Number	Ampere Range
	E10480	0.75A to 5A
	J50501694	0.75A to 5A
	JD60156347	0.75A to 5A
	N/A	0.75A to 5A
	N/A	0.75A to 5A

Electrical Characteristics

% of Ampere Rating	Ampere Rating	Opening Time at 25°C
100%	0.75 A to 5 A	4 Hours, Minimum
200%	0.75 A to 5 A	5 Seconds, Maximum

Electrical Specifications

Ampere Rating (A)	Amp Code	Max Voltage Rating (V)	Interrupting Rating (AC/DC) ^{1,4}	Nominal Resistance (Ohms) ²	Nominal Melting I^2t (A ² sec) ³	Agency Approvals				
0.750	.750	250	300 A @ 32 VDC	0.137	0.282	x	x	x	x	x
1.00	001.	250	100 A @ 125 VDC	0.0994	0.611	x	x	x	x	x
1.25	1.25	250	50 A @ 250 VAC	0.0734	1.09	x	x	x	x	x
1.50	01.5	250	50 A @ 250 VDC	0.0589	1.62	x	x	x	x	x
2.00	002.	250	10,000 A @ 86 VDC	0.0453	2.85	x	x	x	x	x
2.50	02.5	125		0.0278	1.29	x	x	x	x	x
3.00	003.	125	300 A @ 32 VDC	0.0223	2.09	x	x	x	x	x
3.15	3.15	125		0.0213	2.40	x	x	x	x	x
3.50	03.5	125	100 A @ 125 VDC	0.0192	2.82	x	x	x	—	x
4.00	004.	125		0.0168	3.60	x	x	x	x	x
5.00	005.	125	50 A @ 125 VAC	0.0137	5.90	x	x	x	x	x

Notes

1. AC Interrupting Rating tested at rated voltage with unity power factor. DC Interrupting Rating tested with time constant <0.8 ms for 32 VDC, <2.2 ms for 86 VDC, <0.22 ms for 125 VDC, and <0.1 ms for 250 VDC.

2. Nominal Resistance measured with <10% rated current.

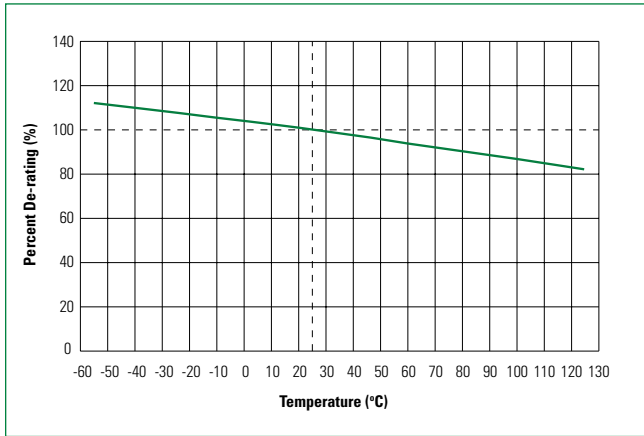
3. Nominal Melting I^2t measured at 1 msec. opening time.

4. Interrupting Rating may differ based on Agency Approval. See Agency Approval certificate for more details.

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Temperature Re-rating Curve



Notes: Re-rating depicted in this curve is in addition to the standard re-rating of 25% for continuous operation.

Example:

For continuous operation at 85 °C, the fuse should be rerated as follows:

$$I = (0.75)(0.90)_{N} = (0.675)_{N}$$

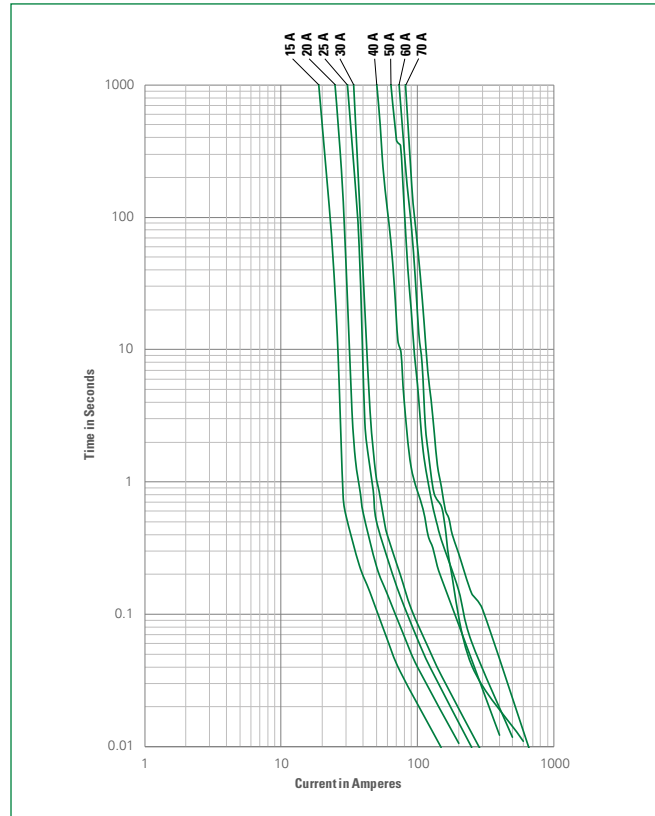
Pulse Cycle Withstand Capability

No. of Pulses to withstand	Ratio of Pulse I ² t to Nominal I ² t
100,000	Pulse I ² t = 18% of Nominal Melting I ² t
10,000	Pulse I ² t = 29% of Nominal Melting I ² t
1,000	Pulse I ² t = 38% of Nominal Melting I ² t
100	Pulse I ² t = 48% of Nominal Melting I ² t

Note

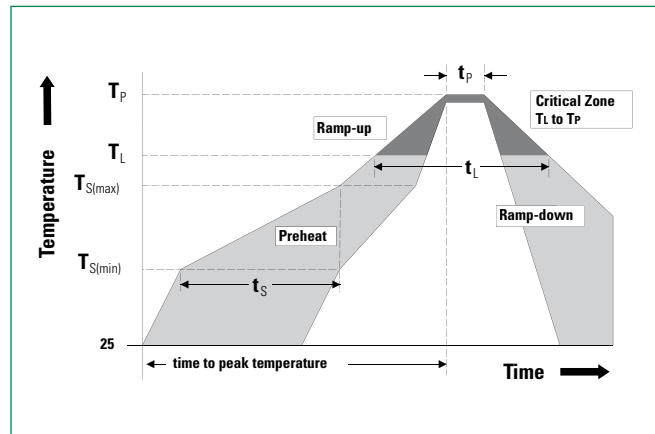
* Being tested

Average Time Current Curves



Soldering Parameters

Reflow Condition		Pb – Free assembly
Pre Heat	- Temperature Min (T _{s(min)})	150 °C
	- Temperature Max (T _{s(max)})	200 °C
	- Time (Min to Max) (t _s)	60–180 secs
Average ramp up rate (Liquidus Temp (T_L) to peak		5 °C/second max.
T_{S(max)} to T_L - Ramp-up Rate		5 °C/second max.
Reflow	- Temperature (T _L) (Liquidus)	217 °C
	- Temperature (t _L)	60–150 secs
Peak Temperature (T_p)		260+0/-5 °C
Time within 5 °C of actual peak Temperature (t_p)		10–30 seconds
Ramp-down Rate		6 °C/second max.
Time 25 °C to peak Temperature (T_p)		8 minutes max.
Do not exceed		260 °C
Wave Soldering Parameters		260 °C Peak Temperature, 10 seconds max.



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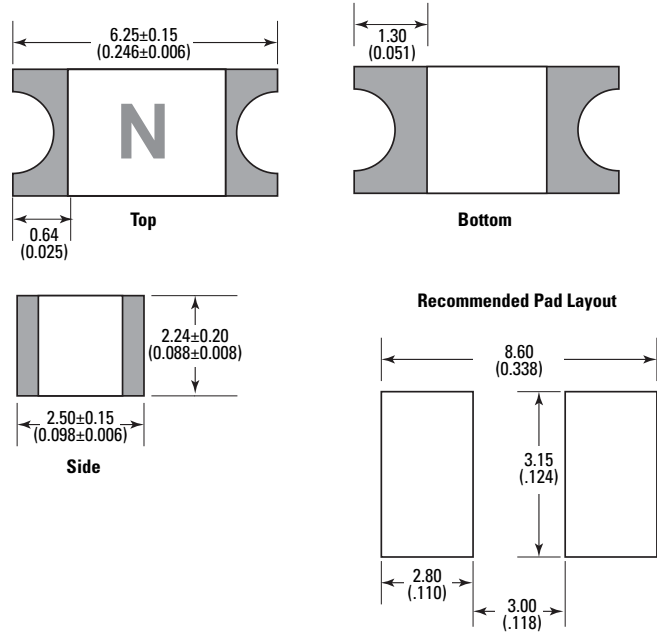
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Product Characteristics

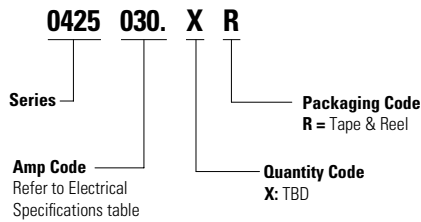
Materials	Body: Epoxy Resin Terminations: Cu/Ni/Sn (100% Pb-free)
Product Marking	Body: Ampere Marking Code. See Part Marking
Insulation Resistance	IEC 60127-4 (0.1 MΩ Min.)
High Temperature Storage	MIL-STD-202, Method 108
Thermal Shock Test	JESD22 Method A104C
Biased Humidity	MIL-STD-202, Method 103, 85 °C/85% RH with 10% operating power for 1000 hrs
Operational Life	MIL-STD-202, Method 108, Test Condition D
Resistance to Solvents	MIL-STD-202, Method 215
Mechanical Shock	MIL-STD-202, Method 213, Test Condition C
High Frequency Vibration	MIL-STD-202, Method 204
Resistance to Soldering Heat	MIL-STD-202, Method 210 (Test K modified)
Solderability	JESD22-B102E Method 1
Moisture Resistance	MIL-STD-202 Method 106
Moisture Sensitivity Level 1	IPC/JEDEC J-STD-020D Level 1
Terminal Strength	AEC Q200-006
Board Bend/Flex	AEC Q200-005

Dimensions

All dimensions in mm (in)



Part Numbering System



Packaging

Packaging Option	Packaging Specification	Quantity	Quantity & Packaging Code
Tape and Reel	EIA-481	1000	MR

Part Marking System

Amp Code	Marking Code
.750	G
001.	H
1.25	J
01.5	K
002.	N
02.5	O
003.	P
3.15	B
03.5	C
004.	S
005.	T

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